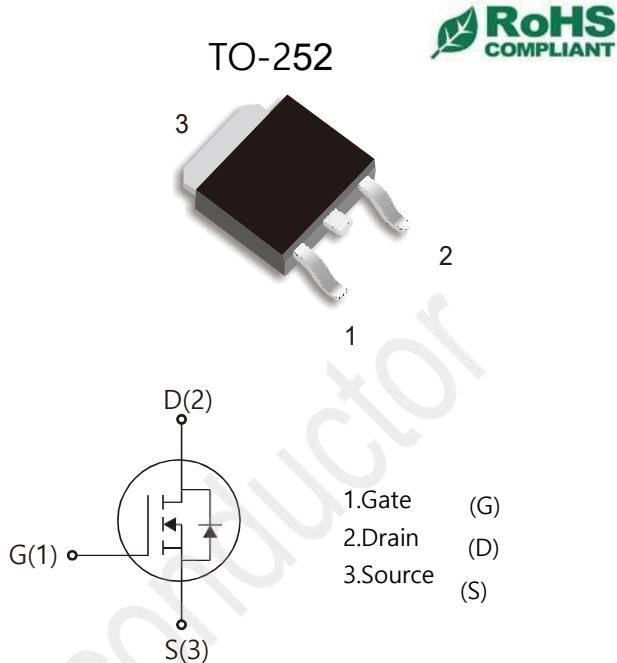




## WGD7N60SE

### Features:

- Low Intrinsic Capacitances.
- Excellent Switching Characteristics.
- Extended Safe Operating Area.
- Unrivalled Gate Charge : $Q_g = 29\text{nC}$  (Typ.).
- $V_{DSS} = 600\text{ V}$ ,  $I_D = 7\text{A}$
- $R_{DS(on)} : 1.3\ \Omega$  (Max) @  $V_G = 10\text{V}$
- 100% Avalanche Tested



### Absolute Maximum Ratings (Ta=25°C unless otherwise noted)

Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain-Source Voltage	600	V
$I_D$	Drain Current	7.0	A
		4.7	
$V_{GSS}$	Gate-Source Voltage	$\pm 30$	V
$E_{AS}$	Single Pulse Avalanche Energy (note1)	300	mJ
$I_{AR}$	Avalanche Current (note2)	7.0	A
$P_D$	Power Dissipation ( $T_j = 25\text{ }^\circ\text{C}$ )	50	W
$T_j$	Junction Temperature(Max)	150	$^\circ\text{C}$
$T_{stg}$	Storage Temperature	-55~+150	$^\circ\text{C}$
$T_L$	Maximum lead temperature for soldering purpose, 1/8' from case for 5 seconds	300	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JC}$	Thermal Resistance,Junction to Case	-	2.4	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance,Junction to Ambient	-	62.5	$^\circ\text{C}/\text{W}$

## Electrical Characteristics (Ta=25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
Off Characteristics						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> =250μA , V <sub>GS</sub> =0	600	-	-	V
△BV <sub>DSS</sub> / △TJ	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> =250μA , Reference to 25°C	-	0.67	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =600V, V <sub>GS</sub> =0V	-	-	10	μA
		V <sub>DS</sub> =480V, T <sub>j</sub> =125°C			100	
I <sub>GSSF</sub>	Gate-body leakage Current, Forward	V <sub>GS</sub> = +30V, V <sub>DS</sub> =0V	-	-	100	nA
I <sub>GSSR</sub>	Gate-body leakage Current, Reverse	V <sub>GS</sub> = -30V, V <sub>DS</sub> =0V	-	-	-100	
On Characteristics						
V <sub>GS(TH)</sub>	Date Threshold Voltage	I <sub>D</sub> =250μA,V <sub>DS</sub> =V <sub>GS</sub>	2	-	4	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	I <sub>D</sub> =3.5A,V <sub>GS</sub> =10V	-	1.2	1.3	Ω
Dynamic Characteristics						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V , V <sub>GS</sub> =0 , f=1.0MHz	-	1000	-	pF
C <sub>oss</sub>	Output Capacitance		-	95	-	
C <sub>rss</sub>	Reverse Transfer Capacitance		-	2.4	-	
Switching Characteristics						
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =310V , I <sub>D</sub> =7A R <sub>G</sub> =25Ω (Note 3,4)	-	30	70	nS
T <sub>r</sub>	Turn-On Rise Time		-	80	170	
T <sub>d(of f)</sub>	Turn-Off Delay Time		-	65	140	
T <sub>f</sub>	Turn-Off Rise Time		-	60	130	
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =480V,V <sub>GS</sub> =10V , I <sub>D</sub> =7A (Note3,4)	-	29	38	nC
Q <sub>gs</sub>	Gate-Source Charge			7	-	
Q <sub>gd</sub>	Gate-Drain Charge		-	14.5	-	
Drain-Source Diode Characteristics and Maximum Ratings						
I <sub>s</sub>	Max. Diode Forward Current	-		--	7	A
I <sub>SM</sub>	Max. Pulsed Forward Current	-		--	28	
V <sub>SD</sub>	Diode Forward Voltage	I <sub>D</sub> =7A	-	-	1.4	V
T <sub>rr</sub>	Reverse Recovery Time	I <sub>s</sub> =7A,V <sub>GS</sub> =0V diF/dt=100A/ μs (Note3)	-	293	-	nS
Q <sub>rr</sub>	Reverse Recovery Charge		-	1.7	-	μC

Notes : 1, L=0.5mH, IAS= 7A, VDD=50V, RG=25Ω, Starting TJ =25°C

2, Repetitive Rating : Pulse width limited by maximum junction temperature

3, Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 2%

4, Essentially Independent of Operating Temperature

## Typical Characteristics

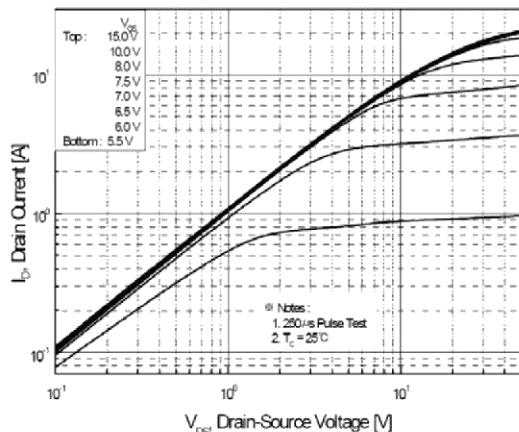


Figure 1. On-Region Characteristics

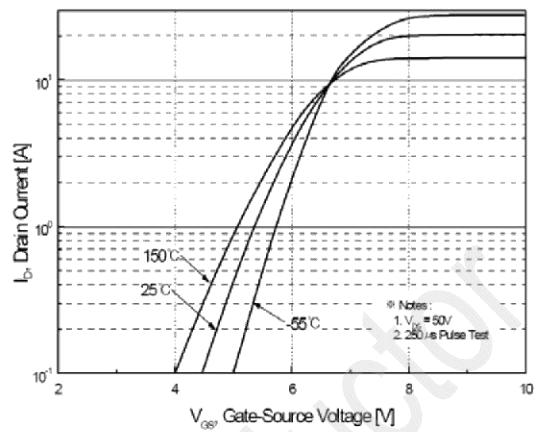


Figure 2. Transfer Characteristics

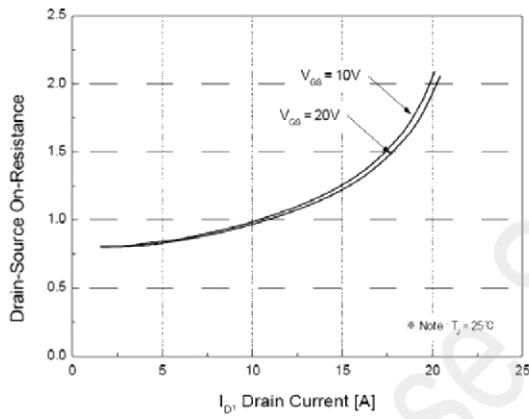


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

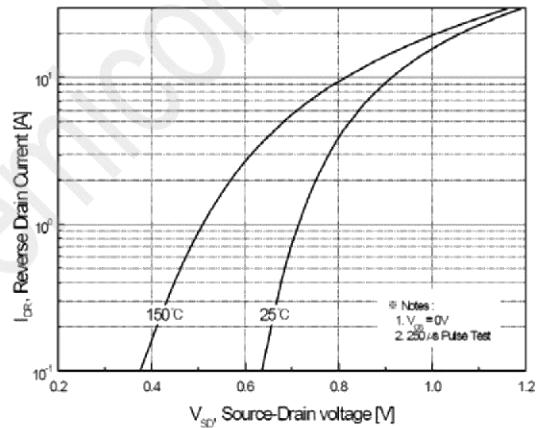


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

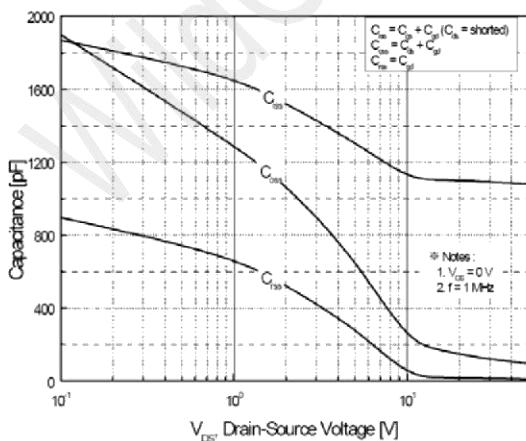


Figure 5. Capacitance Characteristics

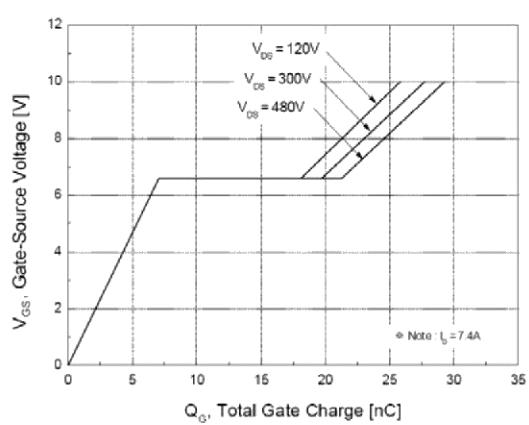
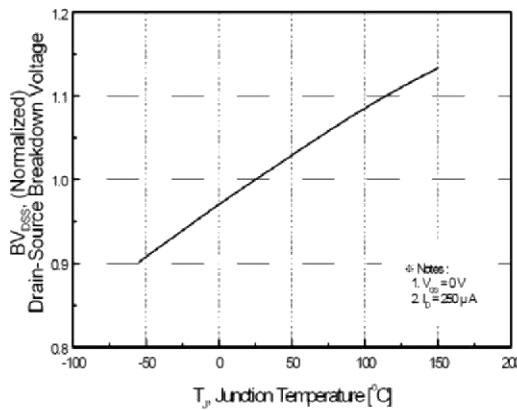
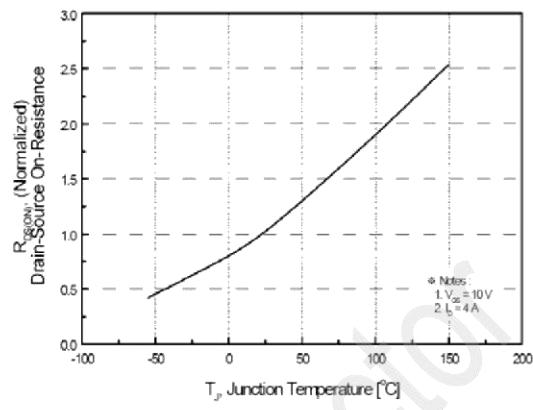


Figure 6. Gate Charge Characteristics

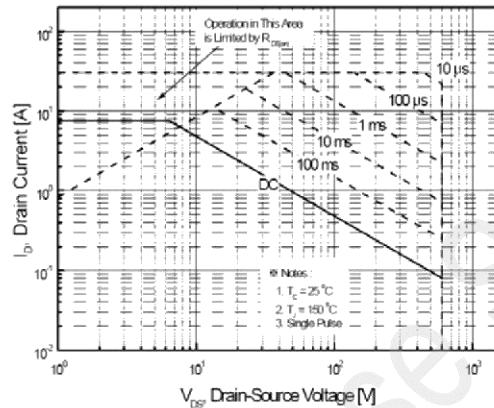
## Typical Characteristics (Continued)



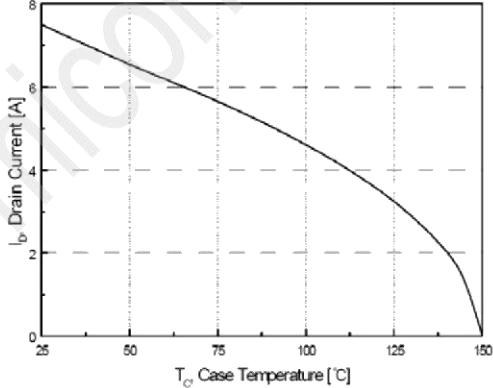
**Figure 7. Breakdown Voltage Variation vs Temperature**



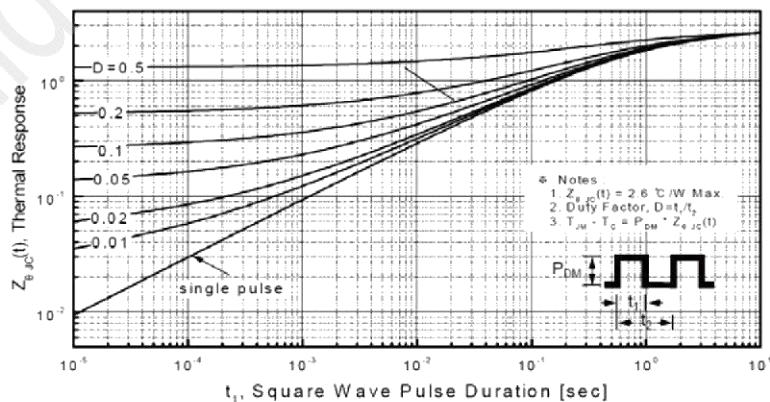
**Figure 8. On-Resistance Variation vs Temperature**



**Figure 9-2. Maximum Safe Operating Area**

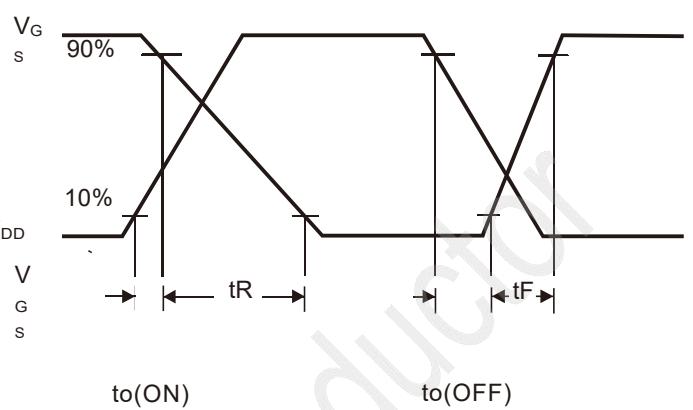
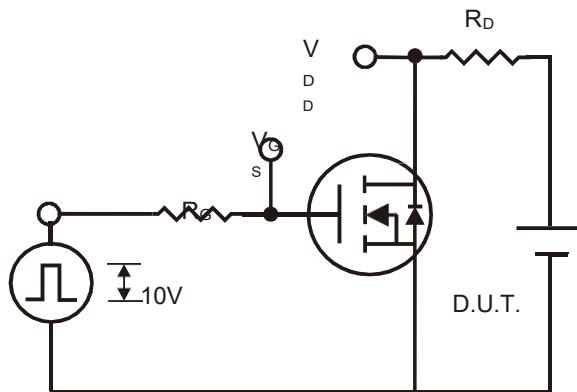


**Figure 10. Maximum Drain Current vs Case Temperature**

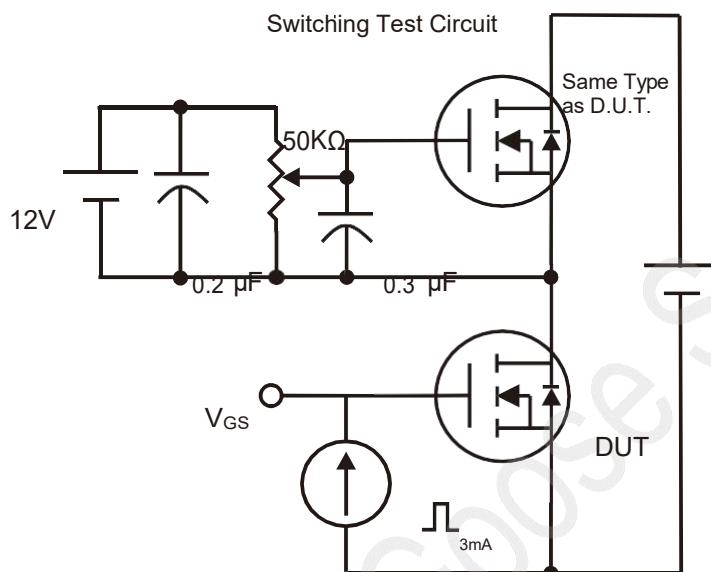


**Figure 11-2. Transient Thermal Response Curve**

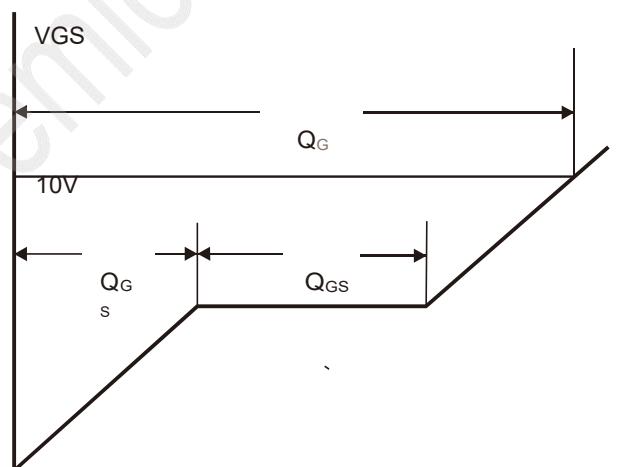
## Gate Charge Test Circuit &amp; Waveform



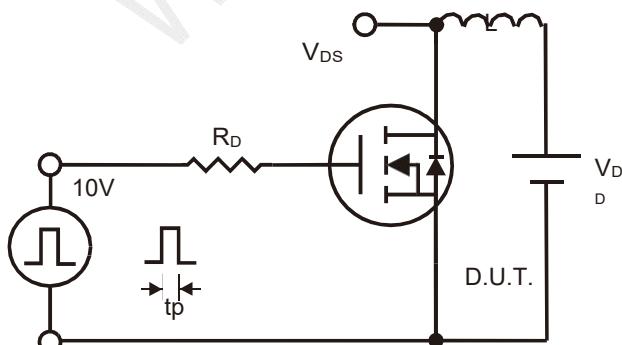
## Switching Test Circuit



## Switching Waveforms

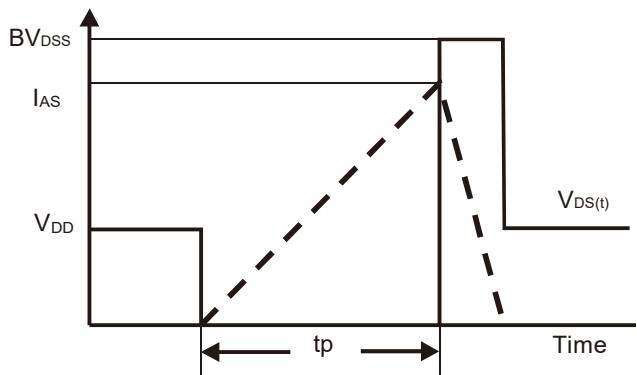


## Gate Charge Test Circuit



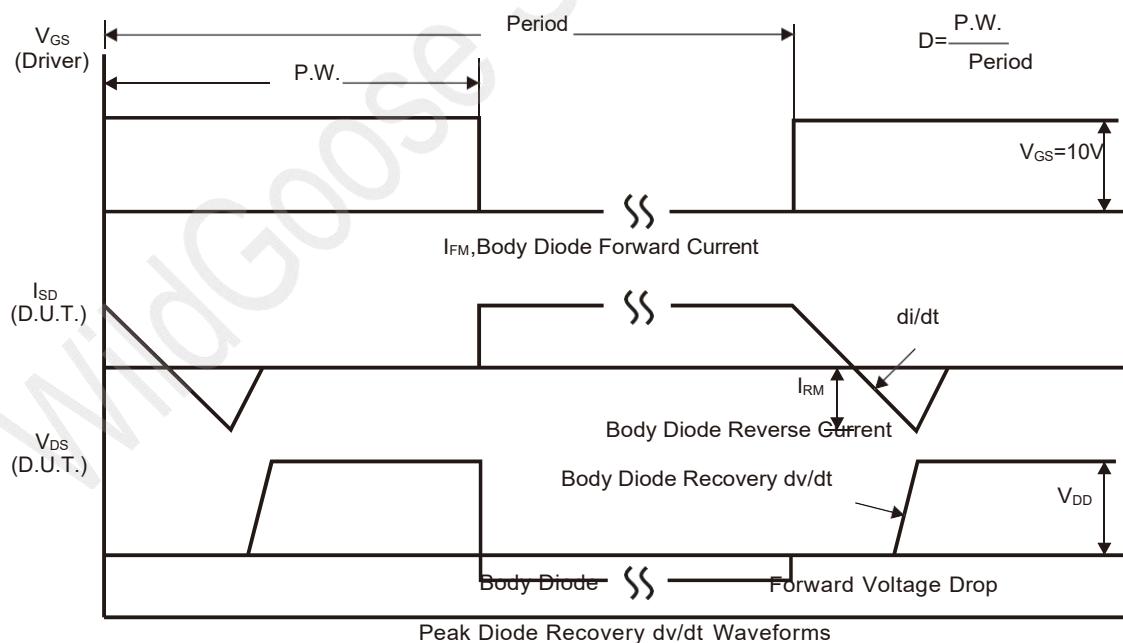
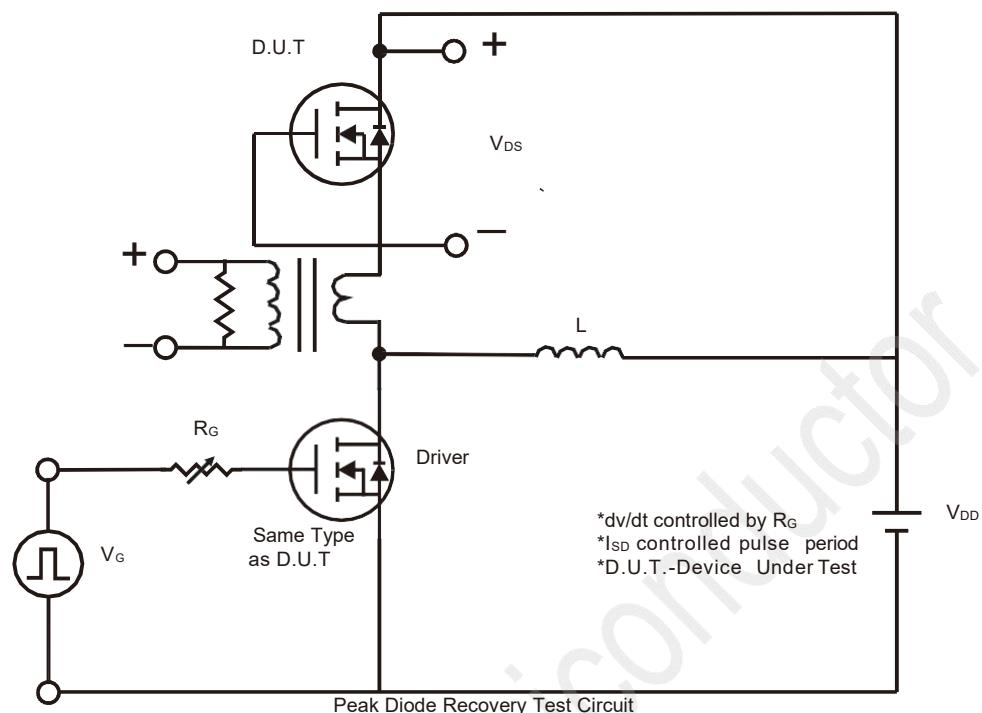
Unclamped Inductive Switching Test Circuit

## Gate Charge Waveform



Unclamped Inductive Switching Waveforms

## Peak Diode Recovery dv/dt Test Circuit &amp; Waveform



Package Dimension

TO-252

Unit: mm

